Features

- Fast Read Access Time – 70 ns
- Automatic Page Write Operation
  - Internal Address and Data Latches for 64 Bytes
- Fast Write Cycle Times
  - Page Write Cycle Time: 10 ms Maximum (Standard)
    2 ms Maximum (Option – Ref. AT28HC64BF Datasheet)
  - 1 to 64-byte Page Write Operation
- Low Power Dissipation
  - 40 mA Active Current
  - 100 µA CMOS Standby Current
- Hardware and Software Data Protection
- $\overline{\text{DATA}}$ Polling and Toggle Bit for End of Write Detection
- High Reliability CMOS Technology
  - Endurance: 100,000 Cycles
  - Data Retention: 10 Years
- Single 5 V ±10% Supply
- CMOS and TTL Compatible Inputs and Outputs
- JEDEC Approved Byte-wide Pinout
- Industrial Temperature Ranges
- Green (Pb/Halide-free) Packaging Option

64K (8K x 8) High Speed Parallel EEPROM with Page Write and Software Data Protection

AT28HC64B

1. Description

The AT28HC64B is a high-performance electrically-erasable and programmable read-only memory (EEPROM). Its 64K of memory is organized as 8,192 words by 8 bits. Manufactured with Atmel's advanced nonvolatile CMOS technology, the device offers access times to 55 ns with power dissipation of just 220 mW. When the device is deselected, the CMOS standby current is less than 100 µA.

The AT28HC64B is accessed like a Static RAM for the read or write cycle without the need for external components. The device contains a 64-byte page register to allow writing of up to 64 bytes simultaneously. During a write cycle, the addresses and 1 to 64 bytes of data are internally latched, freeing the address and data bus for other operations. Following the initiation of a write cycle, the device will automatically write the latched data using an internal control timer. The end of a write cycle can be detected by $\overline{\text{DATA}}$ polling of I/O7. Once the end of a write cycle has been detected, a new access for a read or write can begin.

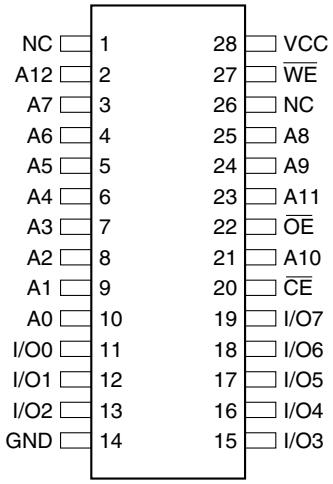
Atmel's AT28HC64B has additional features to ensure high quality and manufacturability. The device utilizes internal error correction for extended endurance and improved data retention characteristics. An optional software data protection mechanism is available to guard against inadvertent writes. The device also includes an extra 64 bytes of EEPROM for device identification or tracking.

0274K–PEEPR–8/08

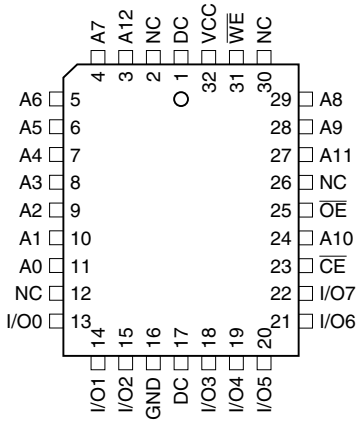
2. Pin Configurations

Pin Name	Function
A0 - A12	Addresses
$\overline{CE}$	Chip Enable
$\overline{OE}$	Output Enable
$\overline{WE}$	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
NC	No Connect
DC	Don't Connect

2.1 28-lead PDIP/SOIC Top View

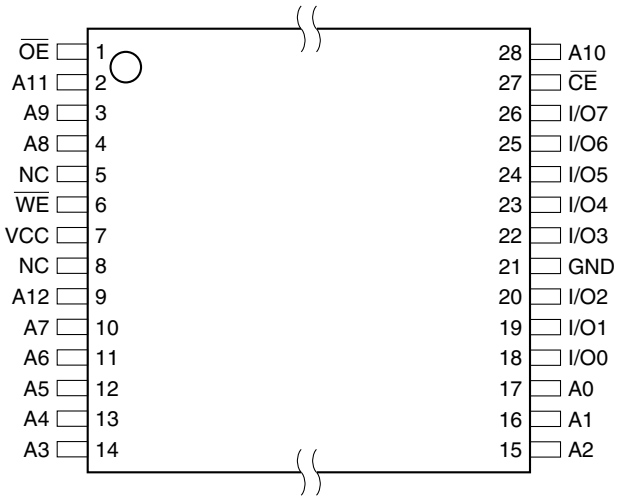


2.2 32-lead PLCC Top View

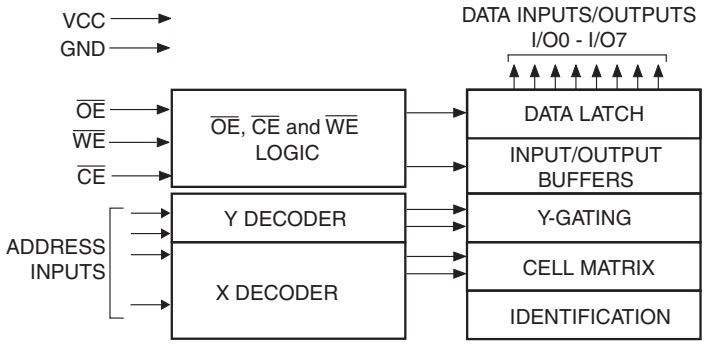


Note: PLCC package pins 1 and 17 are Don't Connect.

2.3 28-lead TSOP Top View



3. Block Diagram



4. Device Operation

4.1 Read

The AT28HC64B is accessed like a Static RAM. When $\overline{CE}$ and $\overline{OE}$ are low and $\overline{WE}$ is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high-impedance state when either $\overline{CE}$ or $\overline{OE}$ is high. This dual line control gives designers flexibility in preventing bus contention in their systems.

4.2 Byte Write

A low pulse on the $\overline{WE}$ or $\overline{CE}$ input with $\overline{CE}$ or $\overline{WE}$ low (respectively) and $\overline{OE}$ high initiates a write cycle. The address is latched on the falling edge of $\overline{CE}$ or $\overline{WE}$, whichever occurs last. The data is latched by the first rising edge of $\overline{CE}$ or $\overline{WE}$. Once a byte write has been started, it will automatically time itself to completion. Once a programming operation has been initiated and for the duration of t_{WC}, a read operation will effectively be a polling operation.

4.3 Page Write

The page write operation of the AT28HC64B allows 1 to 64 bytes of data to be written into the device during a single internal programming period. A page write operation is initiated in the same manner as a byte write; after the first byte is written, it can then be followed by 1 to 63 additional bytes. Each successive byte must be loaded within 150 µs (t_{BLC}) of the previous byte. If the t_{BLC} limit is exceeded, the AT28HC64B will cease accepting data and commence the internal programming operation. All bytes during a page write operation must reside on the same page as defined by the state of the A6 to A12 inputs. For each $\overline{WE}$ high-to-low transition during the page write operation, A6 to A12 must be the same.

The A0 to A5 inputs specify which bytes within the page are to be written. The bytes may be loaded in any order and may be altered within the same load period. Only bytes which are specified for writing will be written; unnecessary cycling of other bytes within the page does not occur.

4.4 $\overline{DATA}$ Polling

The AT28HC64B features $\overline{DATA}$ Polling to indicate the end of a write cycle. During a byte or page write cycle, an attempted read of the last byte written will result in the complement of the written data to be presented on I/O7. Once the write cycle has been completed, true data is valid on all outputs, and the next write cycle may begin. $\overline{DATA}$ Polling may begin at any time during the write cycle.

4.5 Toggle Bit

In addition to $\overline{\text{DATA}}$ Polling, the AT28HC64B provides another method for determining the end of a write cycle. During the write operation, successive attempts to read data from the device will result in I/O6 toggling between one and zero. Once the write has completed, I/O6 will stop toggling, and valid data will be read. Toggle bit reading may begin at any time during the write cycle.

4.6 Data Protection

If precautions are not taken, inadvertent writes may occur during transitions of the host system power supply. Atmel® has incorporated both hardware and software features that will protect the memory against inadvertent writes.

4.6.1 Hardware Protection

Hardware features protect against inadvertent writes to the AT28HC64B in the following ways: (a) V_{CC} sense – if V_{CC} is below 3.8 V (typical), the write function is inhibited; (b) V_{CC} power-on delay – once V_{CC} has reached 3.8 V, the device will automatically time out 5 ms (typical) before allowing a write; (c) write inhibit – holding any one of $\overline{\text{OE}}$ low, $\overline{\text{CE}}$ high or $\overline{\text{WE}}$ high inhibits write cycles; and (d) noise filter – pulses of less than 15 ns (typical) on the $\overline{\text{WE}}$ or $\overline{\text{CE}}$ inputs will not initiate a write cycle.

4.6.2 Software Data Protection

A software-controlled data protection feature has been implemented on the AT28HC64B. When enabled, the software data protection (SDP), will prevent inadvertent writes. The SDP feature may be enabled or disabled by the user; the AT28HC64B is shipped from Atmel with SDP disabled.

SDP is enabled by the user issuing a series of three write commands in which three specific bytes of data are written to three specific addresses (refer to the “Software Data Protection Algorithm” diagram on page 10). After writing the 3-byte command sequence and waiting t_{WC}, the entire AT28HC64B will be protected against inadvertent writes. It should be noted that even after SDP is enabled, the user may still perform a byte or page write to the AT28HC64B. This is done by preceding the data to be written by the same 3-byte command sequence used to enable SDP.

Once set, SDP remains active unless the disable command sequence is issued. Power transitions do not disable SDP, and SDP protects the AT28HC64B during power-up and power-down conditions. All command sequences must conform to the page write timing specifications. The data in the enable and disable command sequences is not actually written into the device; their addresses may still be written with user data in either a byte or page write operation.

After setting SDP, any attempt to write to the device without the 3-byte command sequence will start the internal write timers. No data will be written to the device, however. For the duration of t_{WC}, read operations will effectively be polling operations.

4.7 Device Identification

An extra 64 bytes of EEPROM memory are available to the user for device identification. By raising A9 to 12 V ±0.5 V and using address locations 1FC0H to 1FFFH, the additional bytes may be written to or read from in the same manner as the regular memory array.

5. DC and AC Operating Range

	AT28HC64B-70	AT28HC64B-90	AT28HC64B-120
Operating Temperature (Case)	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C
V_{CC} Power Supply	5 V ±10%	5 V ±10%	5 V ±10%

6. Operating Modes

Mode	$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	I/O
Read	V_{IL}	V_{IL}	V_{IH}	D_{OUT}
Write[2]	V_{IL}	V_{IH}	V_{IL}	D_{IN}
Standby/Write Inhibit	V_{IH}	X[1]	X	High Z
Write Inhibit	X	X	V_{IH}	
Write Inhibit	X	V_{IL}	X	
Output Disable	X	V_{IH}	X	High Z
Chip Erase	V_{IL}	V_H[3]	V_{IL}	High Z

Notes: 1. X can be VIL or VIH.
2. See “AC Write Waveforms” on page 8.
3. VH = 12.0 V ±0.5 V.

7. Absolute Maximum Ratings*

Temperature Under Bias ..... -55°C to +125°C

Storage Temperature ..... -65°C to +150°C

All Input Voltages
(including NC Pins)
with Respect to Ground .....-0.6 V to +6.25 V

All Output Voltages
with Respect to Ground .....-0.6 V to V_{CC} + 0.6 V

Voltage on $\overline{OE}$ and A9
with Respect to Ground .....-0.6 V to +13.5V

*NOTICE: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability

8. DC Characteristics

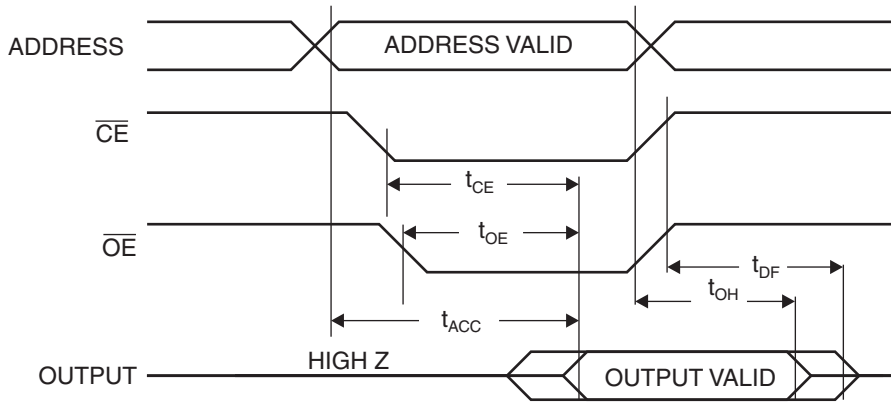
Symbol	Parameter	Condition	Min	Max	Units
I_{LI}	Input Load Current	V_{IN} = 0 V to V_{CC} + 1 V		10	µA
I_{LO}	Output Leakage Current	$V_{I/O}$ = 0 V to V_{CC}		10	µA
I_{SB1}	V_{CC} Standby Current CMOS	$\overline{CE}$ = V_{CC} - 0.3 V to V_{CC} + 1 V		100[1]	µA
I_{SB2}	V_{CC} Standby Current TTL	$\overline{CE}$ = 2.0 V to V_{CC} + 1 V		2[1]	mA
I_{CC}	V_{CC} Active Current	f = 5 MHz; I_{OUT} = 0 mA		40	mA
V_{IL}	Input Low Voltage			0.8	V
V_{IH}	Input High Voltage		2.0		V
V_{OL}	Output Low Voltage	I_{OL} = 2.1 mA		0.40	V
V_{OH}	Output High Voltage	I_{OH} = -400 µA	2.4		V

Note: 1. I_{SB1} and I_{SB2} for the 55 ns part is 40 mA maximum.

9. AC Read Characteristics

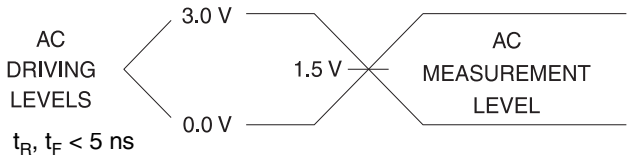
Symbol	Parameter	AT28HC64B-70		AT28HC64B-90		AT28HC64B-120		Units
		Min	Max	Min	Max	Min	Max	
t_{ACC}	Address to Output Delay		70		90		120	ns
t_{CE}[1]	$\overline{CE}$ to Output Delay		70		90		120	ns
t_{OE}[2]	$\overline{OE}$ to Output Delay	0	35	0	40	0	50	ns
t_{DF}[3][4]	$\overline{OE}$ to Output Float	0	35	0	40	0	50	ns
t_{OH}	Output Hold	0		0		0		ns

10. AC Read Waveforms[1][2][3][4]

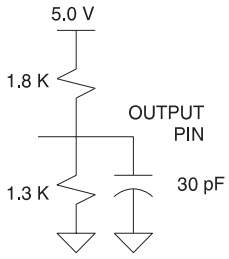


Notes:
1. $\overline{CE}$ may be delayed up to $t_{ACC} - t_{CE}$ after the address transition without impact on t_{ACC}.
2. $\overline{OE}$ may be delayed up to $t_{CE} - t_{OE}$ after the falling edge of $\overline{CE}$ without impact on t_{CE} or by $t_{ACC} - t_{OE}$ after an address change without impact on t_{ACC}.
3. t_{DF} is specified from $\overline{OE}$ or $\overline{CE}$ whichever occurs first (C_L = 5 pF).
4. This parameter is characterized and is not 100% tested.

11. Input Test Waveforms and Measurement Level



12. Output Test Load



13. Pin Capacitance

f = 1 MHz, T = 25°C[1]

Symbol	Typ	Max	Units	Conditions
C_{IN}	4	6	pF	V_{IN} = 0 V
C_{OUT}	8	12	pF	V_{OUT} = 0 V

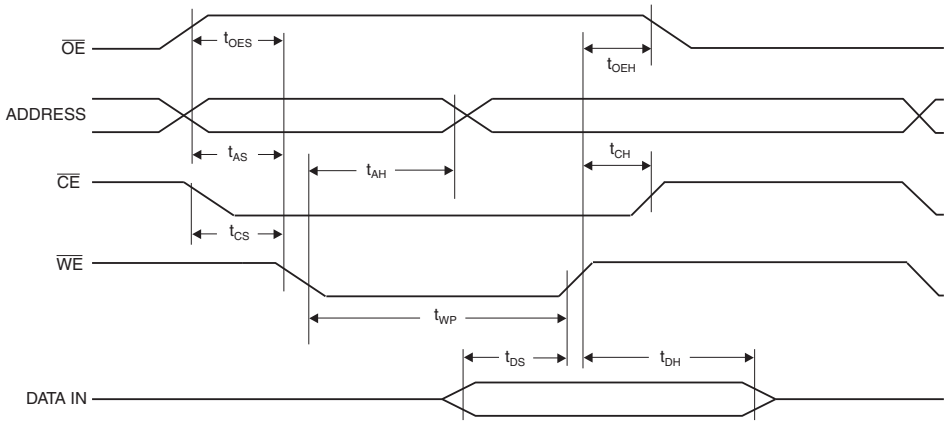
Note: 1. This parameter is characterized and is not 100% tested.

14. AC Write Characteristics

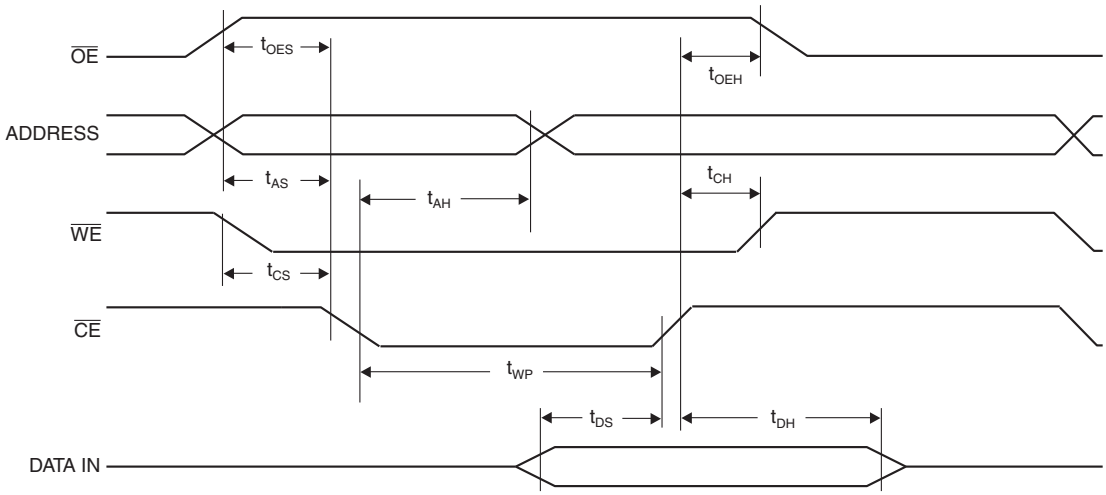
Symbol	Parameter	Min	Max	Units
t_{AS}, t_{OES}	Address, $\overline{OE}$ Setup Time	0		ns
t_{AH}	Address Hold Time	50		ns
t_{CS}	Chip Select Setup Time	0		ns
t_{CH}	Chip Select Hold Time	0		ns
t_{WP}	Write Pulse Width ($\overline{WE}$ or $\overline{CE}$)	100		ns
t_{DS}	Data Setup Time	50		ns
t_{DH}, t_{OEH}	Data, $\overline{OE}$ Hold Time	0		ns

15. AC Write Waveforms

15.1 $\overline{WE}$ Controlled



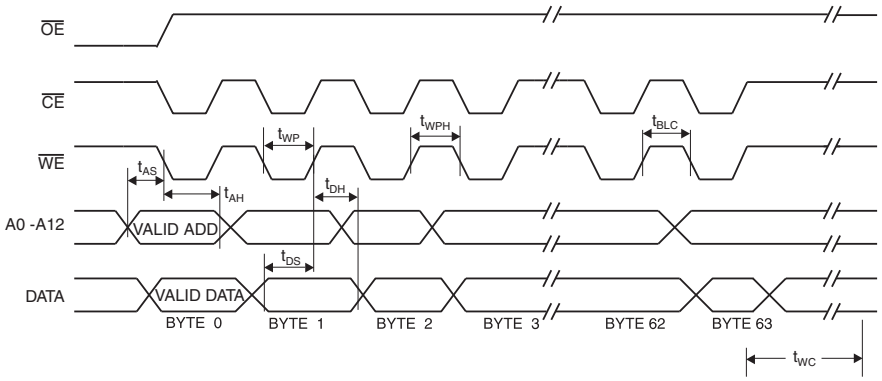
15.2 $\overline{CE}$ Controlled



16. Page Mode Characteristics

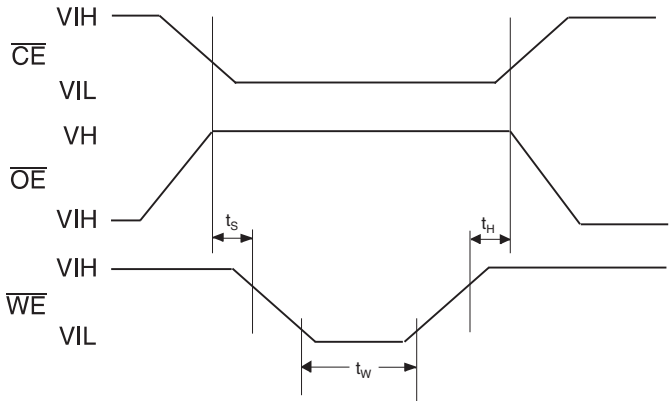
Symbol	Parameter	Min	Max	Units
t_{WC}	Write Cycle Time		10	ms
t_{WC}	Write Cycle Time (Use AT28HC64BF))		2	ms
t_{AS}	Address Setup Time	0		ns
t_{AH}	Address Hold Time	50		ns
t_{DS}	Data Setup Time	50		ns
t_{DH}	Data Hold Time	0		ns
t_{WP}	Write Pulse Width	100		ns
t_{BLC}	Byte Load Cycle Time		150	µs
t_{WPH}	Write Pulse Width High	50		ns

17. Page Mode Write Waveforms(1)(2)



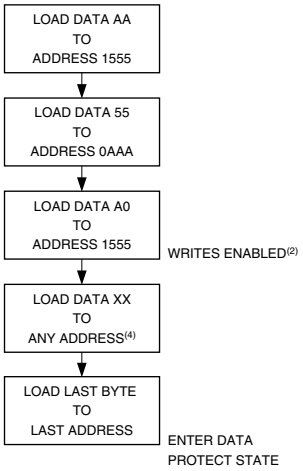
Notes: 1. A6 through A12 must specify the same page address during each high to low transition of $\overline{WE}$ (or $\overline{CE}$).
2. $\overline{OE}$ must be high only when $\overline{WE}$ and $\overline{CE}$ are both low.

18. Chip Erase Waveforms



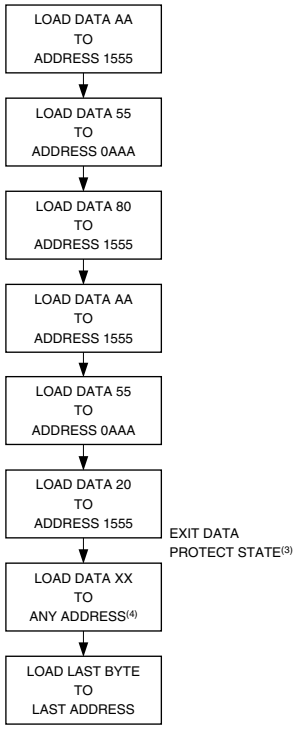
$t_S = t_H = 5$ µs (min.)
$t_W = 10$ ms (min.)
$V_H = 12.0$ V ±0.5 V

19. Software Data Protection Enable Algorithm[1]



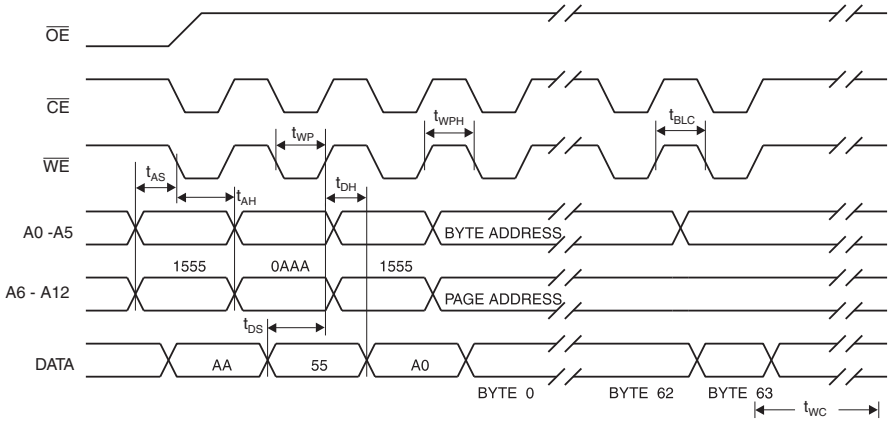
Notes:
1. Data Format: I/O7 - I/O0 (Hex);
   Address Format: A12 - A0 (Hex).
2. Write Protect state will be activated at end of write even if no other data is loaded.
3. Write Protect state will be deactivated at end of write period even if no other data is loaded.
4. 1 to 64 bytes of data are loaded.

20. Software Data Protection Disable Algorithm[1]



Notes:
1. Data Format: I/O7 - I/O0 (Hex);
   Address Format: A12 - A0 (Hex).
2. Write Protect state will be activated at end of write even if no other data is loaded.
3. Write Protect state will be deactivated at end of write period even if no other data is loaded.
4. 1 to 64 bytes of data are loaded.

21. Software Protected Write Cycle Waveforms[1][2]



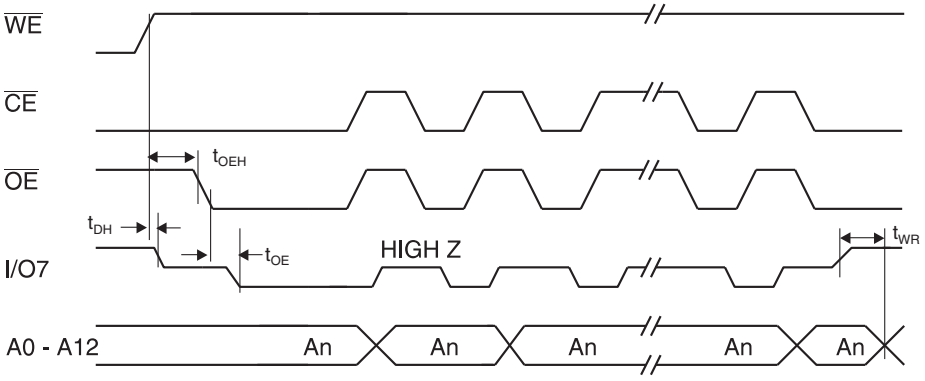
Notes:
1. A6 through A12 must specify the same page address during each high to low transition of $\overline{WE}$ (or $\overline{CE}$) after the software code has been entered.
2. $\overline{OE}$ must be high only when $\overline{WE}$ and $\overline{CE}$ are both low.

22. $\overline{\text{Data}}$ Polling Characteristics[1]

Symbol	Parameter	Min	Typ	Max	Units
t_{DH}	Data Hold Time	0			ns
t_{OEH}	$\overline{OE}$ Hold Time	0			ns
t_{OE}	$\overline{OE}$ to Output Delay[1]				ns
t_{WR}	Write Recovery Time	0			ns

Note: 1. These parameters are characterized and not 100% tested. See “AC Read Characteristics” on page 6.

23. $\overline{\text{Data}}$ Polling Waveforms

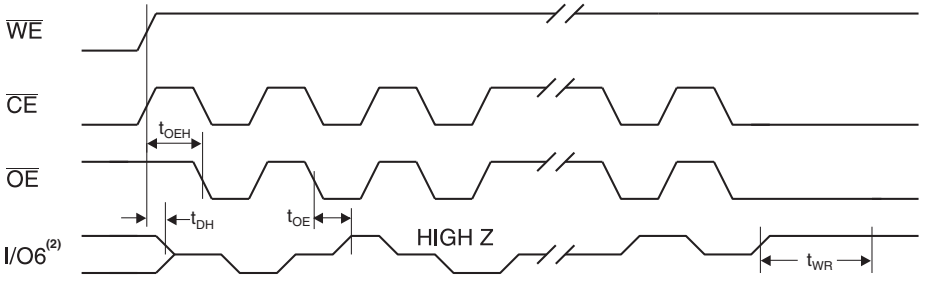


24. Toggle Bit Characteristics[1]

Symbol	Parameter	Min	Typ	Max	Units
t_{DH}	Data Hold Time	10			ns
t_{OEH}	$\overline{OE}$ Hold Time	10			ns
t_{OE}	$\overline{OE}$ to Output Delay[2]				ns
t_{OEHP}	$\overline{OE}$ High Pulse	150			ns
t_{WR}	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.
2. See “AC Read Characteristics” on page 6.

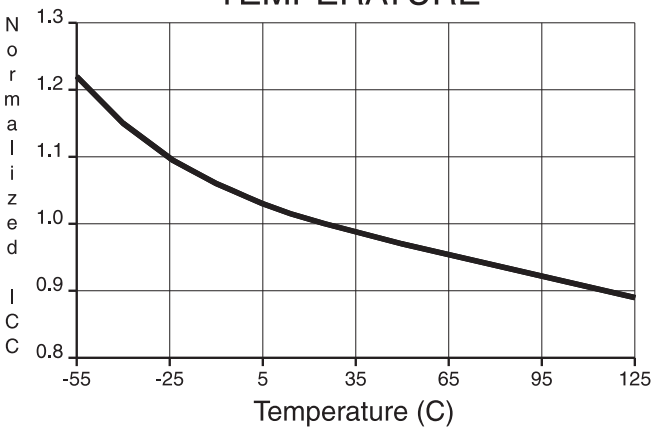
25. Toggle Bit Waveforms[1][2][3]



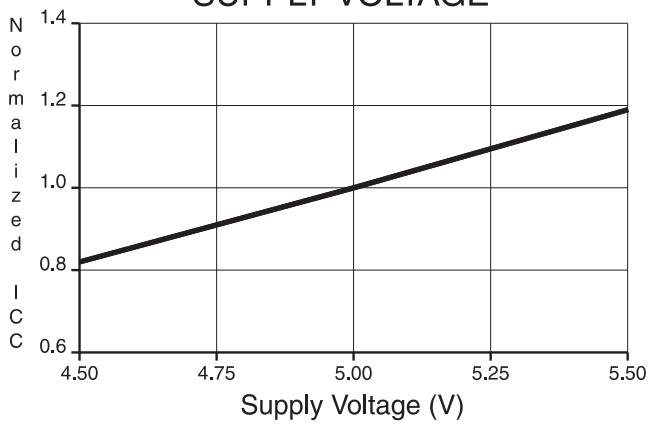
Notes: 1. Toggling either $\overline{OE}$ or $\overline{CE}$ or both $\overline{OE}$ and $\overline{CE}$ will operate toggle bit.
2. Beginning and ending state of I/O6 will vary.
3. Any address location may be used, but the address should not vary.

26. Normalized I_{CC} Graphs

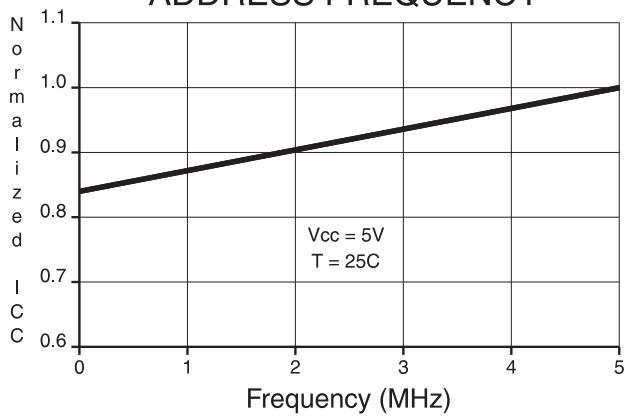
NORMALIZED SUPPLY CURRENT vs. TEMPERATURE



NORMALIZED SUPPLY CURRENT vs. SUPPLY VOLTAGE



NORMALIZED SUPPLY CURRENT vs. ADDRESS FREQUENCY



27. Ordering Information[1]

27.1 Standard Package

t_{ACC} (ns)	I_{CC} (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
70	40	0.1	AT28HC64B-70JI AT28HC64B-70PI AT28HC64B-70SI AT28HC64B-70TI	32J 28P6 28S 28T	Industrial (-40°C to 85°C)
90	40	0.1	AT28HC64B-90JI AT28HC64B-90PI AT28HC64B-90SI AT28HC64B-90TI	32J 28P6 28S 28T	
120	40	0.1	AT28HC64B-12JI AT28HC64B-12PI AT28HC64B-12SI AT28HC64B-12TI	32J 28P6 28S 28T	

Note: 1. See “Valid Part Numbers” on page 13.

27.2 Green Package Option (Pb/Halide-free)

t_{ACC} (ns)	I_{CC} (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
70	40	0.1	AT28HC64B-70TU AT28HC64B-70JU AT28HC64B-70SU	28T 32J 28S	Industrial (-40°C to 85°C)
90	40	0.1	AT28HC64B-90JU AT28HC64B-90PU AT28HC64B-90SU AT28HC64B-90TU	32J 28P6 28S 28T	
120	40	0.1	AT28HC64B-12JU AT28HC64B-12SU	32J 28S	

Package Type	
32J	32-lead, Plastic J-leaded Chip Carrier (PLCC)
28P6	28-lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
28S	28-lead, 0.300" Wide, Plastic Gull Wing Small Outline (SOIC)
28T	28-lead, Plastic Thin Small Outline Package (TSOP)

28. Valid Part Numbers

The following table lists standard Atmel products that can be ordered.

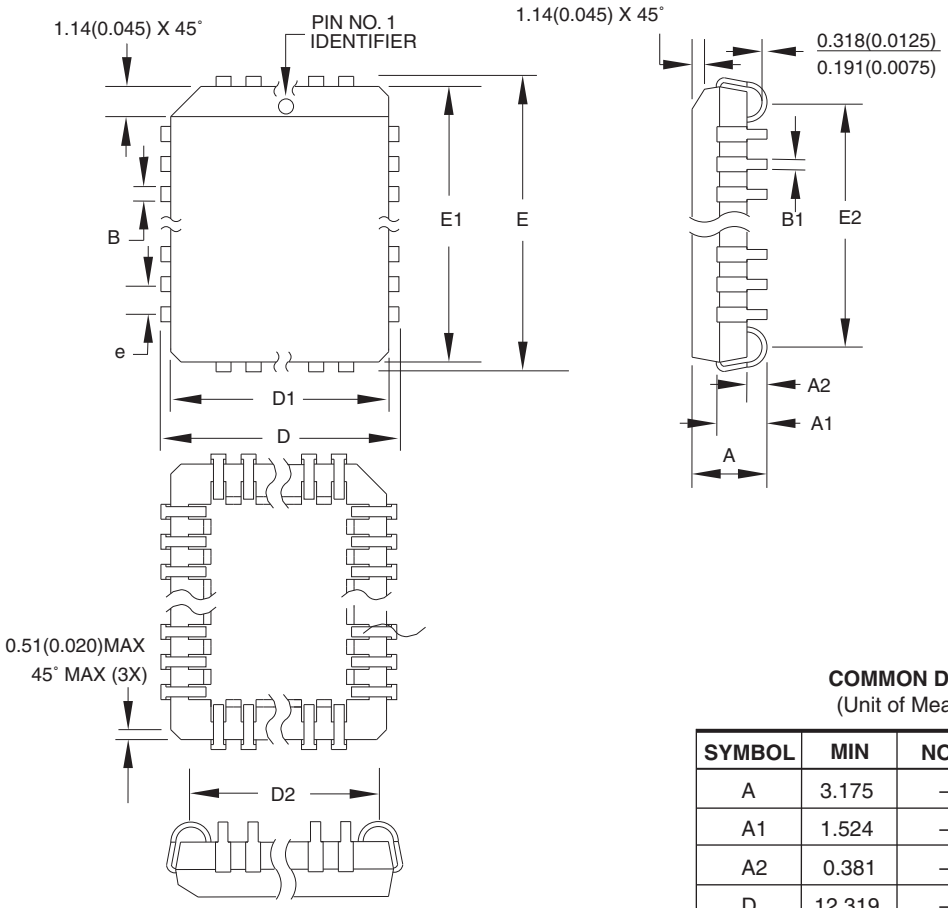
Device Numbers	Speed	Package and Temperature Combinations
AT28HC64B	70	JI, PI, SI, TI, TU, JU, SU
AT28HC64B	90	JI, JU, PI, PU, SI, SU, TI, TU
AT28HC64B	12	JI, JU, PI, PU, SI, SU, TI, TU

29. Die Products

Reference Section: Parallel EEPROM Die Products

30. Packaging Information

30.1 32J – PLCC



COMMON DIMENSIONS
(Unit of Measure = mm)

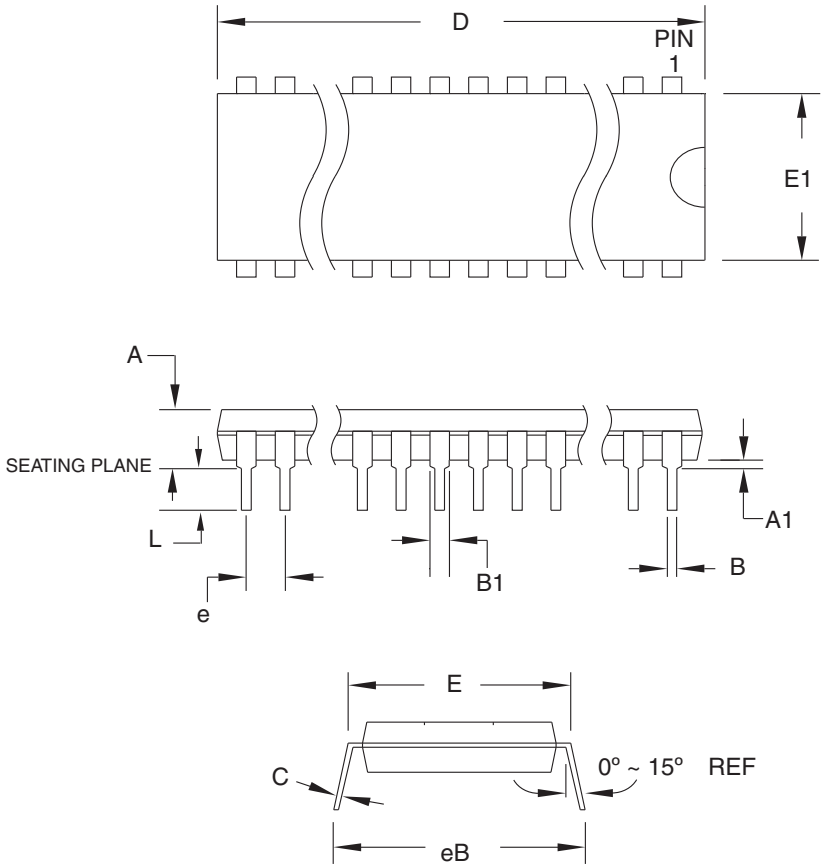
SYMBOL	MIN	NOM	MAX	NOTE
A	3.175	–	3.556	
A1	1.524	–	2.413	
A2	0.381	–	–	
D	12.319	–	12.573	
D1	11.354	–	11.506	Note 2
D2	9.906	–	10.922	
E	14.859	–	15.113	
E1	13.894	–	14.046	Note 2
E2	12.471	–	13.487	
B	0.660	–	0.813	
B1	0.330	–	0.533	
e	1.270 TYP			

Notes:
1. This package conforms to JEDEC reference MS-016, Variation AE.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is .010"(0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
3. Lead coplanarity is 0.004" (0.102 mm) maximum.

10/04/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**32J**, 32-lead, Plastic J-leaded Chip Carrier (PLCC)	32J	B

30.2 28P6 – PDIP



COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	4.826	
A1	0.381	–	–	
D	36.703	–	37.338	Note 2
E	15.240	–	15.875	
E1	13.462	–	13.970	Note 2
B	0.356	–	0.559	
B1	1.041	–	1.651	
L	3.048	–	3.556	
C	0.203	–	0.381	
eB	15.494	–	17.526	
e	2.540 TYP			

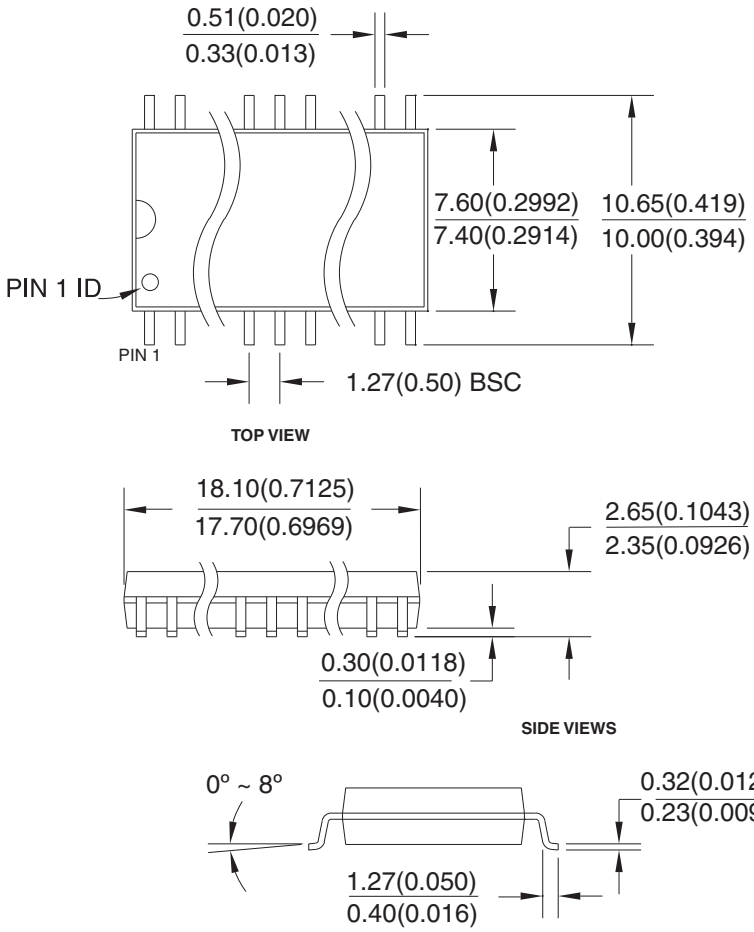
Notes:
1. This package conforms to JEDEC reference MS-011, Variation AB.
2. Dimensions D and E1 do not include mold Flash or Protrusion. Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

09/28/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**28P6**, 28-lead (0.600"/15.24 mm Wide) Plastic Dual Inline Package (PDIP)	28P6	B

30.3 28S – SOIC

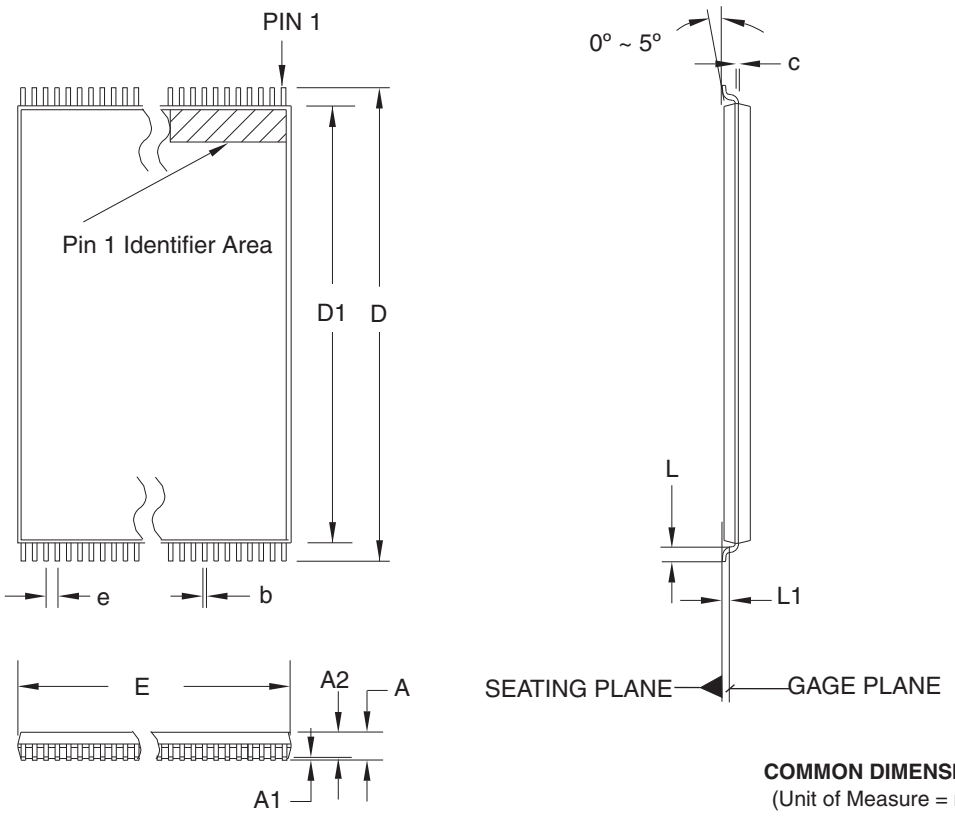
Dimensions in Millimeters and (Inches).
Controlling dimension: Millimeters.



8/4/03

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**28S**, 28-lead, 0.300" Body, Plastic Gull Wing Small Outline (SOIC) JEDEC Standard MS-013	28S	B

30.4 28T – TSOP



COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.20	
A1	0.05	–	0.15	
A2	0.90	1.00	1.05	
D	13.20	13.40	13.60	
D1	11.70	11.80	11.90	Note 2
E	7.90	8.00	8.10	Note 2
L	0.50	0.60	0.70	
L1	0.25 BASIC			
b	0.17	0.22	0.27	
c	0.10	–	0.21	
e	0.55 BASIC			

Notes:
1. This package conforms to JEDEC reference MO-183.
2. Dimensions D1 and E do not include mold protrusion. Allowable protrusion on E is 0.15 mm per side and on D1 is 0.25 mm per side.
3. Lead coplanarity is 0.10 mm maximum.

12/06/02

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**28T**, 28-lead (8 x 13.4 mm) Plastic Thin Small Outline Package, Type I (TSOP)	28T	C

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